

Insulating bush

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| art. no. IB 1 / IBT 1 | art. no. IB 2 / IBT 2 | art. no. IB 3 / IBT 3 | art. no. IB 4 / IBT 4 | art. no. IB 5 |
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| art. no. IB 6 / IBT 6 | art. no. IB 7 / IBT 7 | art. no. IB 8 / IBT 8 | art. no. IB 9 / IBT 9 | art. no. IB 10 / IBT 10 |
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| art. no. IB 11 / IBT 11 | art. no. IB 12 / IBT 12 | art. no. IB 13 | art. no. IB 14 / IBT 14 | art. no. IB 15 / IBT 15 |
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| art. no. IB 16 | art. no. IB 17 | art. no. IB 18 / IBT 18 | | |

| | IB 1 - IB 7 / 18 | IBT 1 - IBT 15 / 18 | IB 8 - IB 17 |
|------------------------------|---------------------------------|----------------------------|---------------------|
| material | polyamide 4.6, GF reinforced | PTFE (teflon) | thermoplastic resin |
| form stability | -40 °C ... +250 °C (1,8 MPa) | -260 °C ... +250 °C | -40 °C ... +200 °C |
| dielectric strength | >30 kV/mm | >40 kV/mm | >38 kV/mm |
| class of flammability | UL 94 V-0 | | |

Mica wafers
Thermal conductive material
Mounting for TO 3 angle
Die-cast heatsinks

→ E 17
→ E 2 - 5
→ A 123
→ A 123 - 126

Aluminium oxide wafers
Thermal conductive paste
Thermal conductive glue
Technical introduction

→ E 15 - 16
→ E 19 - 20
→ E 21 - 22
→ A 2 - 7

E 50

A

B

C

D

E

F

G

H

I

K

L

M

N